

ABSTRACT

The present invention relates to a maleimide resin composition containing (A) one or more selected from the group consisting of a maleimide compound having one or more N-substituted maleimide groups and a derivative thereof; and (B) a polymer having a hydrocarbon chain or a polyether chain in a main chain thereof, wherein the component (A) contains (A1) a maleimide compound having one or more N-substituted maleimide groups and a molecular weight of less than 600 and (A2) a maleimide compound having one or more N-substituted maleimide groups and a molecular weight of 600 or more. The present invention also relates to a prepreg, a laminated board, a resin film, a printed wiring board, and a semiconductor package that are obtained by using the maleimide resin composition.